

Product Change Notification

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Product Change Notification Number: GC230149

Date: January 12th, 2023

Title: EV12AQ600 / 605 migration to lead-free bumps

Product Identification: all EV_12AQ60_SH_ references,

EV12AQ600ACSH	EV12AQ600AMSH-ADX4	EVX12AQ600ASH
EV12AQ600ACSH-ADX4	EV12AQ605ACSH	EVP12AQ600SH
EV12AQ600AVSH	EV12AQ605ACSH-ADX4	EVP12AQ605SH
EV12AQ600AVSH-ADX4	EV12AQ605AVSH	
EV12AQ600AMSH	EV12AQ605AVSH-ADX4	

See also dedicated product page on :

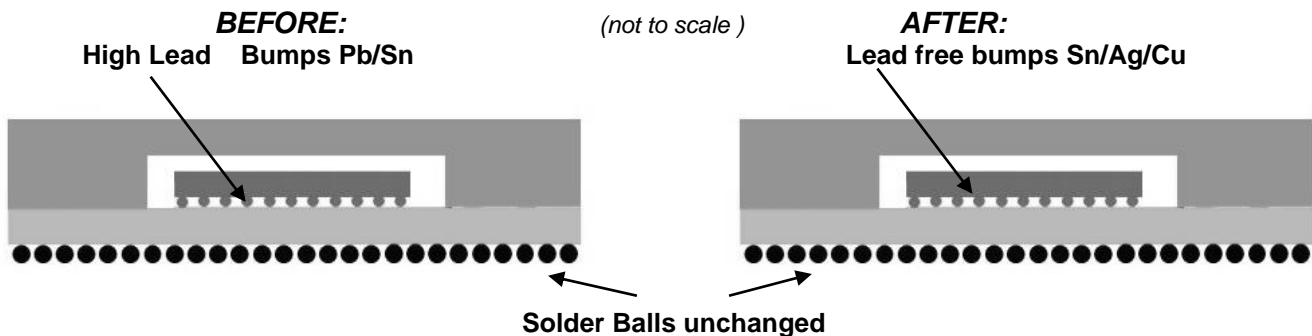
<https://semiconductors.teledyneimaging.com/en/products/data-converters/ev12aq600/>

Reason for Change:

- Other
 Design
 Manufacturing Location
 Processing
 Quality/Reliability
 Logistics
 Material

Change Description:

Teledyne e2v announces the replacement of the leaded bumps by lead free bumps on the EV12AQ600/605 product family. Only bumps (die-to-package) change, solder balls (package-to-board) remain unchanged.



Identification Method to Distinguish Change:

The product change will be identified by a specific package code to distinguish the die bump metallurgy options. "SH" string will be replaced by "UH".

For example, EV12AQ600AMSH becomes EV12AQ600AMUH

Qualification Data for the UH package option:

- available
 will be available in April 2023
 not applicable



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Quantifiable Impact on Quality & Reliability:

This change does not affect the fit, form, functions of the part and the electrical characteristics remain unchanged. The bumps composition is the only material affected by this change. The composition of all other materials used in this product remains unchanged. The die revision remains unchanged. No impact on reliability is expected.

Implementation Date*: Estimated April-2023

Last orders to Teledyne e2v for the SH package must be placed until 12-APRIL-2023 to comply with above deadline. Teledyne e2v shipments shall be no later than September 2023.

Lead-time shall be confirmed at order entry.

**The Estimated Implementation Date is the forecasted date that a customer may expect to receive changed product. This is determined by the estimated date of inventory depletion on the PCN issue date. This may be affected by fluctuations in supply and demand. Consequently, although customers should be prepared to receive changed product on this date, Teledyne e2v semiconductors SAS will continue to ship pre-changed product until a time in which inventory has been depleted. This may result in pre-changed product being shipped to customers after this forecasted date.*

Teledyne e2v semiconductors SAS contact:

	Quality	Marketing
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Would you need further information, please contact also your local Teledyne e2v sales representative for your product availability requirements

APPROVAL

Teledyne e2v semiconductors SAS will deem this change accepted unless specific conditions of acceptance are provided in writing within 30 days from the date of this notice. All correspondence must be sent to the contact e-mail addresses indicated above.

Teledyne e2v semiconductors SAS assumes no responsibility for any errors that may appear in this document.

The supply of products will be subject to Teledyne e2v semiconductors SAS general terms and conditions of sale or any specific contractual terms agreed between the parties.

If you would like to see already available announcements or receive customer notifications by email, please subscribe to our customer notification mailing list via:

<https://semiconductors.teledyneimaging.com/en/products/lifecycle-management-obsolescence/>